Research and technological development: setting up the ENIAC Joint Undertaking, nanoelectronics

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The Council held an exchange of views on four proposals aimed at establishing joint technology initiatives (JTIs) in the following fields:

- nano-electronics technologies ("**ENIAC**")
- aeronautics and air transport ("CLEAN SKY") (CNS/2007/0118)
- innovative medicines ("IMI") (CNS/2007/0089)
- embedded computing systems ("ARTEMIS") (CNS/2007/0088)

The ministerial debate concentrated in horizontal issues with a view to adopting final decisions at the November Competitiveness Council meeting in order to enable a swift start to the four JTIs in 2008.

The Council underlined a number of important political elements which resulted from the

discussion:

- The JTIs should be set up under Community law as Community bodies. They should receive Community funding in order to implement the research programmes, notably by awarding funding to selected projects, following publication of calls for proposals.
- They will take the form of real public/private partnerships with a shared responsibility of industry in the management of the joint undertakings. EU member states and the Commission will exercise appropriate supervision over the use of public funds.
- They will have a limited duration of 10 years.
- They will not have the status of international organisations.
- They will have legal personality and will be established on the basis of articles 171 and 172 of the EC treaty.
- They will implement the research programmes by combining public and private funding.
- The Community will contribute to both the research activities and the running costs.
- The Council also tasked the preparatory bodies to continue further technical work based on the political guidelines agreed by the Council.

To recall, the ENIAC initiative will address the need for silicon-based technologies throughout four technology domains: the shrinking of logic and memory devices to increase performance and reduce costs; the development of value-added functions, include sensing, actuating and packaging functions and their embedding with logic and memory to form complex system-on-chip or system-in-package solutions; equipment and materials and design automation.

The maximum of the Community contribution is estimated at EUR 450 million (up to 2017).